MICROELECTRONIC PACKAGES WITH SMALL FOOTPRINTS AND ASSOCIATED METHODS OF MANUFACTURING

ABSTRACT

Several embodiments of stacked-die microelectronic packages with small footprints and associated methods of manufacturing are disclosed herein. In one embodiment, the package includes a substrate, a first die carried by the substrate, and a second die between the first die and the substrate. The first die has a first footprint, and the second die has a second footprint that is smaller than the first footprint of the first die. The package further includes an adhesive having a first portion adjacent to a second portion. The first portion is between the first die and the second die, and the second portion being between the first die and the substrate.

(Figure 2)